

REV.	SPECIFICATION	ECN NO.	APPD.
X4			

Materials and Plating:

Housing: LCP, UL94V-0, Black.
 Contact: Copper Alloy.
 5u" Gold Plated on Contact Area and Gold Flash on Solder Tail over 50u" Nickel.

Electrical Characteristics:

Current Rating: 0.5 AMP.
 Dielectric Withstanding: AC 500V for 1 Minute.
 Insulation Resistance: 500MΩ min. at DC 150V.
 Contact Resistance: 30mΩ max.at DC 100mA.
 Operating Temperature: -40°C ~ +125°C
***RoHS Compliant**

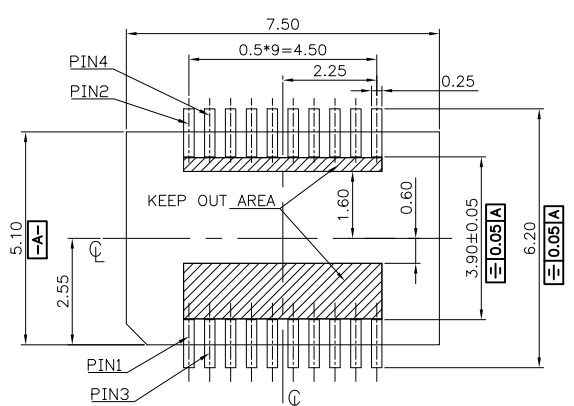
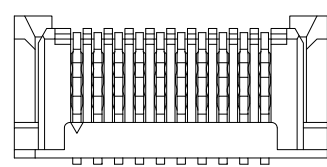
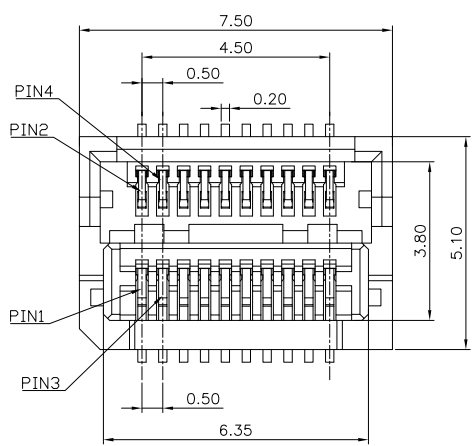
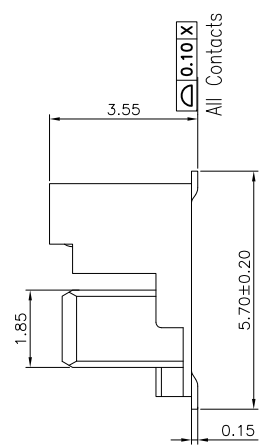
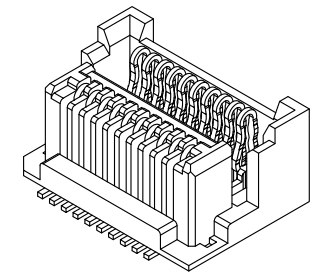
Support Speed Rates to 20Gbps @-3dB.

Note 1:

Refer to IPC 7525-A for stencil creation.

Note 2:

Practical connector height is not the dimensional height of the connector but the height as it pertains to total stack height. An example is a connector with a 2mm practical connector height, when mated to itself will resulting in a board to board stack height of 4mm.



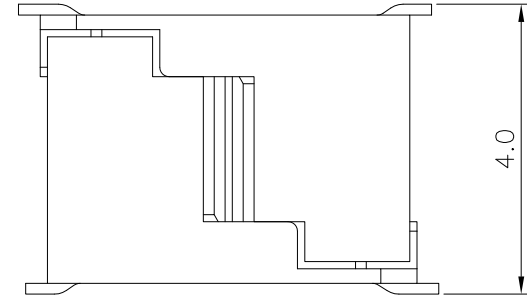
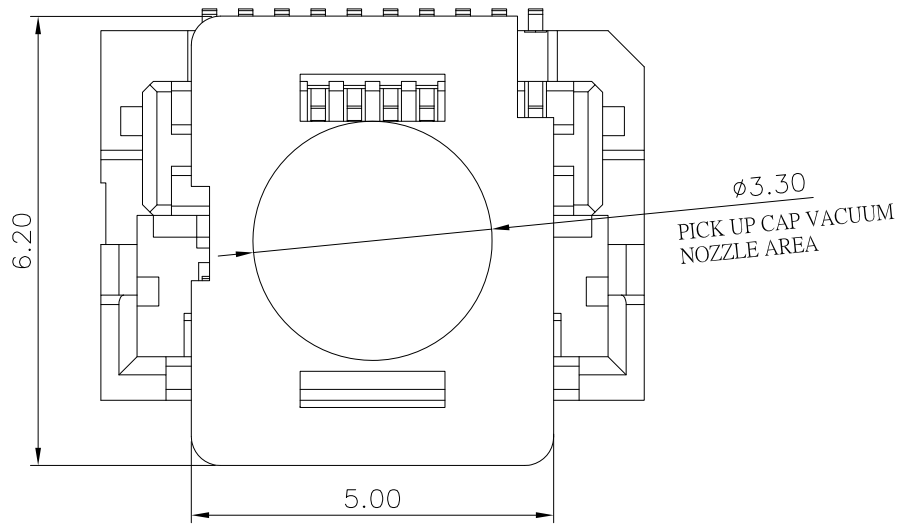
P.C.Board Layout
(Tolerance:±0.05)

Series 2330- 20 G 05 D N 1 T -P
 No. of Position
 G: Gold Plated
 05: 5u"
 D: SMD Type
 N: Without Post
 T: Tape & Reel Package
 P: With Plastic Cap
 1: Practical connector Height=2.0mm

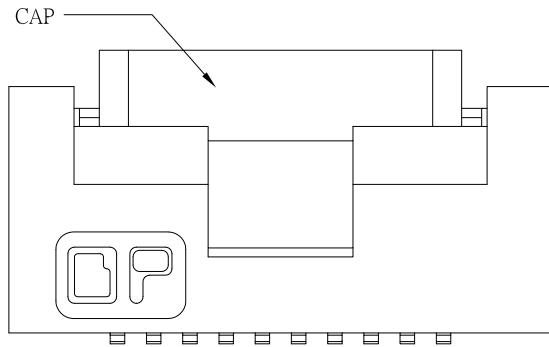
HERMAPHRODITIC CONNECTOR MATING	
CONNECTOR POSITION	MATES WITH CONNECTOR POSITION
1	2
3	4
5	6
7	8
9	10
ETC.	

Tolerances	Dwg. No.	2330-DS20-001	Title:	2330 Series Board to Board 0.5mm Pitch	 OUPIIN ELECTRONIC(KUNSHAN) CO., LTD. P/N: 2330-20G05DN1T-P
x = ±0.5	Projection				
.x = ±0.25	Unit	mm	Scale 1:1		
.xx = ±0.15	Drawn By	GYJ 09/07/20'		SHEET 1/2	Ver.No. X4

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CONNECTOR ASSEMBLY



SHOWN WITH PICK-UP CAP

Tolerances	Dwg. No.	2330-DS20-001	Title:		OUPIN OUPIN ELECTRONIC(KUNSHAN) CO., LTD.
x = ±0.5	Projection		2330 Seires		
.x = ±0.25	Unit	mm	Scale	1:1	P/N: 2330-20G05DN1T-P
.xx = ±0.15	Drawn By	GYJ 09/7/20'			SHEET 2/2
					Ver.No. X4